



Material Content Data Sheet



Sales Product Name		ICE3BR2280JZ-T		Issued		29. August 2013		
MA#		MA001049478						
Package		PG-DIP-7-3		Weight*		645.24 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.427	0.69	0.69	6861	6861
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		6001	
wire	non noble metal	copper	7440-50-8	157.218	24.37	25.01	243659	250035
	noble metal	gold	7440-57-5	0.393	0.06	0.06	610	610
	encapsulation	organic material	carbon black	1333-86-4	2.345	0.36		3634
encapsulation	plastics	epoxy resin	-	63.316	9.81		98128	
	inorganic material	silicondioxide	60676-86-0	403.344	62.51	72.68	625111	726873
leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10011	10011
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2471	2471
glue	plastics	epoxy resin	-	0.354	0.05		549	
	noble metal	silver	7440-22-4	1.671	0.26	0.31	2590	3139
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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